



Material Content Data Sheet



Halogen-Free

Sales Product Name	IPTC012N08NM5	Issued	23. June 2021
MA#	MA005447212		
Package	PG-HDSOP-16-2	Weight*	855.58 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	7.727	0.90	0.90	9032	9032
leadframe	inorganic material	phosphorus	7723-14-0	0.143	0.02		167	
	non noble metal	iron	7439-89-6	0.477	0.06		558	
	non noble metal	copper	7440-50-8	476.748	55.72	55.80	557225	557950
wire	non noble metal	aluminium	7429-90-5	20.743	2.42	2.42	24244	24244
encapsulation	inorganic material	zinc oxide	1314-13-2	3.227	0.38		3771	
	miscellaneous	miscellaneous	-	12.906	1.51		15085	
	plastics	epoxy resin	-	48.399	5.66		56569	
	inorganic material	silicon dioxide	60676-86-0	258.129	30.17	37.72	301702	377127
lead finish	non noble metal	tin	7440-31-5	6.684	0.78	0.78	7812	7812
plating	inorganic material	phosphorus	7723-14-0	0.013			15	
	non noble metal	nickel	7440-02-0	5.316	0.62	0.62	6213	6228
solder	non noble metal	tin	7440-31-5	0.125	0.01		146	
	noble metal	silver	7440-22-4	0.156	0.02		183	
	non noble metal	lead	7439-92-1	5.973	0.70	0.73	6981	7310
heatspreader	inorganic material	phosphorus	7723-14-0	0.003			3	
	non noble metal	iron	7439-89-6	0.009			10	
	non noble metal	copper	7440-50-8	8.798	1.03	1.03	10284	10297
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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